

## 2005 IEEE Workshop on Charge-Coupled Devices and Advanced Image Sensors Participants

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Arakawa, Kenichi	Toshiba Corporation, Japan
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Fossum, Eric R.	Siimpel Corporation, USA
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Fujita, Hiroaki	Eastman Kodak Company, USA
Fukushima, Tatsuyuki	Teradyne K.K., Japan
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Kawahito, Shoji  
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Kondo, Yasushi  
Konishi, Masahiro  
Korobov, Vladimir  
Krymski, Alexander  
Kwon, Ohbong  
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Toshiba Corporation, Japan  
Matsushita Electric Industrial Co.,Ltd., Japan  
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Konica Minolta Technology Center, Inc., Japan  
Rockwell Scientific, USA  
MtekVision Co., Ltd, Korea  
Nara Institute of Science and Technology, Japan  
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Sony Corporation, Japan  
Teradyne K.K., Japan  
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Fuji Photo Film Co.,Ltd., Japan  
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Alexima, USA  
MagnaChip Semiconductor Ltd., Korea  
Korea Institute for Advanced Study, Korea  
Pixelplus Semiconductor, USA  
LG Electronics Institute of Technology, Korea  
CSEM, Switzerland  
TSMC North America, USA  
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**Workshop Participants List Revision**

Agranov, Gennady A. Micron Technology, Inc., USA	→	Agranov, Gennadiy A. Micron Technology, Inc., USA
Henderson, Robert Kerr ST Microelectronics, UK	→	Henderson, Robert Kerr University of Edinburgh, UK
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Roks, Edwin DALSA Corporation, The Netherlands	→	Korthout, Laurens DALSA Corporation, The Netherlands
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Murata, Hironobu Kodak Japan Ltd, Japan	→	(canceled)

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